# 505497807 05/29/2019

# PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 EPAS ID: PAT5544611

Stylesheet Version v1.2

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
CHIHIRO UEMATSU	03/26/2019
HIROKO FUJITA	03/20/2019
AKIRA MASUYA	03/20/2019

### **RECEIVING PARTY DATA**

Name:	HITACHI HIGH-TECHNOLOGIES CORPORATION	
Street Address:	24-14, NISHI SHIMBASHI 1-CHOME, MINATO-KU,	
City:	TOKYO	
State/Country:	JAPAN	
Postal Code:	1058717	

### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	16464830

### **CORRESPONDENCE DATA**

**Fax Number:** (703)684-1157

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

**Phone:** 703-684-1120

Email: svannarath@mmiplaw.com
Correspondent Name: MATTINGLY & MALUR, PC
Address Line 1: 1800 DIAGONAL ROAD

Address Line 2: SUITE 210

Address Line 4: ALEXANDRIA, VIRGINIA 22314

ATTORNEY DOCKET NUMBER:	H&A-12143
NAME OF SUBMITTER:	JOHN R. MATTINGLY
SIGNATURE:	/John R. Mattingly/
DATE SIGNED:	05/29/2019

**Total Attachments: 1** 

source=12143\_ASN#page1.tif

PATENT 505497807 REEL: 049305 FRAME: 0336

## ASSIGNMENT (譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me by HITACHI HIGH-TECHNOLOGIES CORPORATION, a corporation organized under the laws of Japan,

located at 24-14, Nishi Shimbashi 1-chome, Minato-ku, Tokyo, Japan

receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI HIGH-TECHNOLOGIES CORPORATION, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

#### **CULTURE INSTRUMENT**

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, No. PCT/JP2016/087301 filed December 14, 2016, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said HITACHI HIGH-TECHNOLOGIES CORPORATION,

its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI HIGH-TECHNOLOGIES CORPORATION.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (発明者フルネームサイン)		Date Signed (署名日)
1)	Chiho Umorn	3/26/2019
	Chihiro UEMATSU	
2)	Kiroko Fujita	3/20/2019
	Hiroko FUJITA	
3)	Okira Masuya	3/20/2019
	Akira MASUYA	

PATENT REEL: 049305 FRAME: 0337

RECORDED: 05/29/2019